

### Abstract of the Disclosure

Medical devices can be formed from medical device components that are bonded together with an adhesive that resists stresses caused by adhesive curing. In particular, a medical device can include a first component and a second component. The second  
5 component can be configured to fit at least partially over the first component. An aerated adhesive layer can be formed or disposed between the first and second components.

**CERTIFICATE UNDER 37 C.F.R. 1.10:** The undersigned hereby certified that this paper or papers, as described herein are being deposited in the United States Postal Service, "Express Mail Post Office to Addressee" having an Express Mail mailing label number of: EV 315613630 US, in an envelope addressed to: Mail Stop Patent Application, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on this 8th day of April 2004.

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